

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A semiconductor device comprising:  
an antenna, antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;  
an integrated circuit comprising a thin film ~~transistor~~, transistor;  
~~a light-emitting element, and~~  
a light-receiving element configured to receive a second optical signal; and  
a light-emitting element configured to transmit a third optical signal,  
wherein the light-emitting element and the light-receiving element each have a layer for conducting photoelectric conversion using a non-single crystal thin film, and  
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit.
  
2. (Currently Amended) A semiconductor device comprising:  
an antenna, antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;  
an integrated circuit comprising a thin film ~~transistor~~, transistor;  
~~a light-emitting element, and~~  
a light-receiving element configured to receive a second optical signal; and  
a light-emitting element configured to transmit a third optical signal,  
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and  
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally.

3. (Currently Amended) A semiconductor device comprising:

~~an antenna,~~ antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;

an integrated circuit comprising a thin film ~~transistor,~~ transistor;

~~a light-emitting element, and~~

a light-receiving element configured to receive a second optical signal; and

a light-emitting element configured to transmit a third optical signal,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed integrally.

4. (Currently Amended) A semiconductor device comprising:

an integrated ~~circuit,~~ circuit;

~~a light-emitting element, and~~

a light-receiving element configured to receive a first optical signal; and

a light-emitting element configured to transmit a second optical signal,

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating ~~[[a]]~~ the first optical signal received in the light-receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a ~~second~~ third signal,

wherein the light-emitting element ~~can convert~~ converts the ~~second~~ third signal to ~~[[an]]~~ the second optical signal, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally.

5. (Currently Amended) A semiconductor device comprising:

~~an antenna,~~ antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;

an integrated circuit comprising a thin film ~~transistor,~~ transistor;

~~a light-emitting element, and~~

a light-receiving element configured to receive a second optical signal; and

a light-emitting element configured to transmit a third optical signal,

wherein the light-emitting element and the light-receiving element each have a layer for conducting photoelectric conversion using a non-single crystal thin film,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

6. (Currently Amended) A semiconductor device comprising:

~~an antenna,~~ antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;

an integrated circuit comprising a thin film ~~transistor,~~ transistor;

~~a light-emitting element, and~~

a light-receiving element configured to receive a second optical signal; and

a light-emitting element configured to transmit a third optical signal,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

7. (Currently Amended) A semiconductor device comprising:

~~an antenna,~~ antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;

an integrated circuit comprising a thin film ~~transistor,~~ transistor;

~~a light-emitting element, and~~

a light-receiving element configured to receive a second optical signal; and

a light-emitting element configured to transmit a third optical signal,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

8. (Currently Amended) A semiconductor device comprising:

an integrated ~~circuit,~~ circuit;

~~a light-emitting element, and~~

a light-receiving element configured to receive a first optical signal; and

a light-emitting element configured to transmit a second optical signal,

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating ~~[[a]]~~ the first optical signal received in the light-receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a ~~second~~ third signal,

wherein the light-emitting element ~~can convert~~ converts the ~~second~~ third signal to ~~[[an]]~~ the second optical signal,

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

9. (Original) A semiconductor device according to any one of Claims 5 to 8, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.

10. (Currently Amended) An IC card comprising:

~~an antenna,~~ antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;

~~an integrated circuit comprising a thin film transistor,~~ transistor;

~~a light-emitting element, and~~

~~a light-receiving element~~ configured to receive a second optical signal; and

~~a light-emitting element configured to transmit a third optical signal,~~

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally.

11. (Original) An IC card according to claim 10, wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed integrally.

12. (Currently Amended) An IC card comprising:

~~an integrated circuit,~~ circuit;

~~a light-emitting element, and~~

a light-receiving element configured to receive a first optical signal; and

a light-emitting element configured to transmit a second optical signal,

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating [[a]] the first optical signal received in the light-receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a ~~second~~ third signal,

wherein the light-emitting element ~~can convert~~ converts the ~~second~~ third signal to [[an]] the second optical signal, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally.

13. (Currently Amended) An IC card comprising:

~~an antenna,~~ antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;

an integrated circuit comprising a thin film ~~transistor,~~ transistor;

~~a light-emitting element, and~~

a light-receiving element configured to receive a second optical signal; and

a light-emitting element configured to transmit a third optical signal,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

14. (Currently Amended) An IC card according to claim 13, wherein the ~~antenna~~, antenna and the integrated circuit, circuit in addition to the light-emitting element and the light-receiving element are formed over ~~[[a]]~~ the first substrate and then separated therefrom, and attached to ~~[[a]]~~ the second substrate.

15. (Original) An IC card according to claim 12, wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

16. (Original) The IC card according to any one of Claims 13 to 15, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.